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DSAFG01

Silicon PNP epitaxial planar type

For High-frequency Amplifier

Marking Symbol A4

Package Code : ML3-N4-B

Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	-30	V
Collector-emitter voltage (Base open)	VCEO	-20	V
Emitter-base voltage (Collector open)	VEBO	-5	V
Collector current	IC	-30	mA
Collector power dissipation	Pc	100	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Pin name	1.	Base
	2.	Emitter
	3.	Collector

Electrical Characteristics Ta = 25 °C±3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base cutoff current (Emitter open)	ICBO	VCB = -10 V, IE = 0			-0.1	µA
Collector-emitter cutoff current (Base open)	ICEO	VCE = -20 V, IB = 0			-100	µA
Emitter-base cutoff current (Collector open)	IEBO	VEB = -5 V, IC = 0			-10	µA
Forward current transfer ratio *1	hFE	VCE = -10 V, IC = -1 mA	70		220	-
Collector-emitter saturation voltage	VCE(sat)	IC = -10 mA, IB = -1 mA		-0.1		V
Base-emitter voltage	VBE	VCE = -10 V, IC = -1 mA		-0.7		V
Transition frequency	fT	VCE = -10 V, IC = -1 mA	150	300		MHz
Small-signal revers transfer capacitance	Cre	VCE = -10 V, IC = -1mA, f = 10.7 MHz		1.0		pF
Noise figuer	NF	VCE = -10 V, IC = -1 mA, f = 5 MHz		2.8		dB
Feedback impedance	Zrb	VCE = -10 V, IC = -1 mA, f = 2 MHz		22		Ω

Note: Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

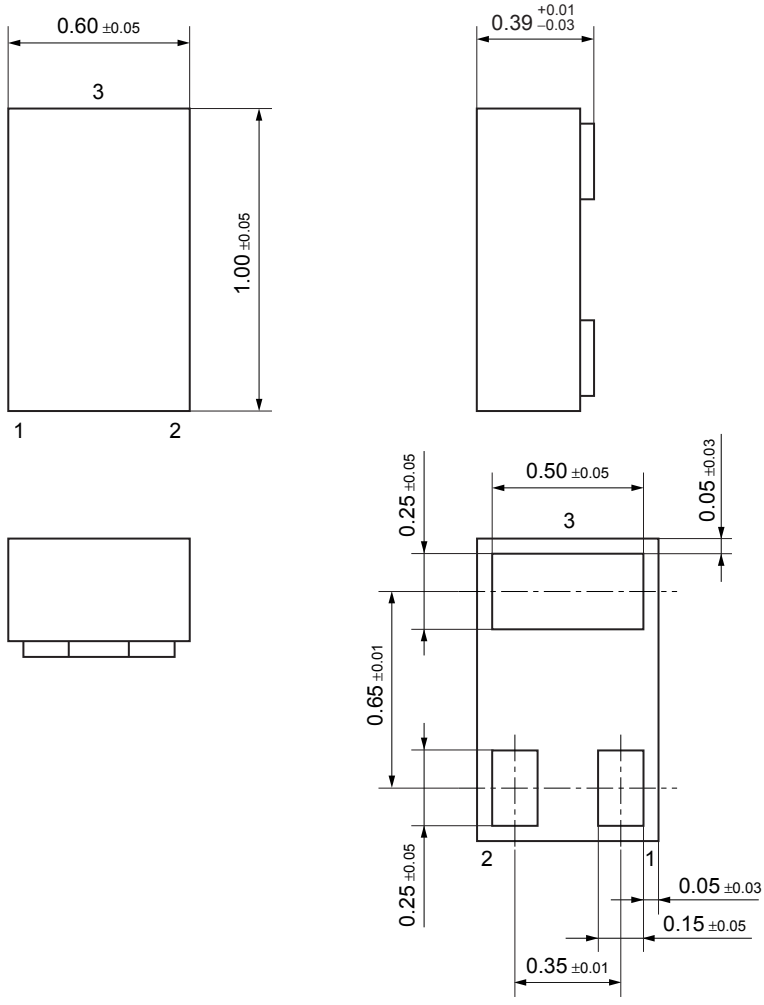
Packing

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel

2010.2.24	2010.7.27	
Prepared	Revised	

ML3-N4-B

Unit: mm



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